# 2015 37th Electrical Overstress/Electrostatic Discharge Symposium (EOS/ESD 2015)

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Moderator: Christian Russ, Intel Mobile Communications

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Moderator: Mototsugu Okushima, Renasas



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## 9A: ESD Testing and Failure Analysis

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# Workshops

Workshops Chair – James Miller, Freescale Semiconductor, Inc.

## Workshop Session A



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